

24M01A = Specific Device Code

A = Assembly Location

Y = Production Year (Last Digit)

M = Production Month $(1-9, \overline{0}, \overline{N}, D)$

XXX = Last Three Digits of Assembly Lot Number

MARKING DIAGRAMS

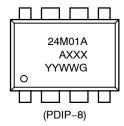


M0L = Specific Device Code A = Assembly Location Code

LL = Assembly Lot Number Y = Year

M = Month

= Pb-Free Package



24M01A = Specific Device Code

A = Assembly Location XXX = Last Three Digits of Assembly Lot Number

YY = Production Year (Last Two Digits)

WW = Production Week (Two Digits)

G = Pb-Free Designator

Table 1. ABSOLUTE MAXIMUM RATINGS

Parameters	Ratings	Units
Storage Temperature	−65 to +150	°C
Voltage on any Pin with Respect to Ground (Note 1)	−0.5 to +6.5	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. The DC input voltage on any pin should not be lower than -0.5 V or higher than $V_{CC} + 0.5$ V. During transitions, the voltage on any pin may undershoot to no less than -1.5 V or overshoot to no more than $V_{CC} + 1.5$ V, for periods of less than 20 ns.

Table 2. RELIABILITY CHARACTERISTICS (Note 2)

Symbol	Parameter	Min	Units
N _{END} (Notes 3, 4)	Endurance	1,000,000	Program/Erase Cycles
T _{DR}	Data Retention	100	Years

- 2. These parameters are tested initially and after a design or process change that affects the parameter according to appropriate AEC-Q100 and JEDEC test methods.
- 3. Test Condition: Page Mode, V_{CC} = 5 V, 25°C.
- 4. The device uses ECC (Error Correction Code) logic with 6 ECC bits to correct one bit error in 4 data bytes. Therefore, when a single byte has to be written, 4 bytes (including the ECC bits) are re-programmed. It is recommended to write by multiple of 4 bytes in order to benefit from the maximum number of write cycles.

Table 3. D.C. OPERATING CHARACTERISTICS

 V_{CC} = 1.8 V to 5.5 V, T_A = -40°C to +85°C and V_{CC} = 2.5 V to 5.5 V, T_A = -40°C to +125°C, unless otherwise specified.

Symbol	Parameter	Test Conditions		Min	Max	Units
I _{CCR}	Read Current	Read, f _{SCL} = 400 kHz / 1 MHz	7		1	mA
I _{CCW}	Write Current	V _{CC} = 1.8 V			3.5	mA
		V _{CC} = 5.5 V			5.0	1
I _{SB}	Standby Current	All I/O Pins at GND or V _{CC}	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$		2	μΑ
			$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$		5	
ΙL	I/O Pin Leakage	Pin at GND or V _{CC}	Pin at GND or V_{CC} $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$		1	μΑ
			$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$		2	
V _{IL1}	Input Low Voltage	$2.5~V \leq V_{CC} \leq 5.5~V$	•	-0.5	0.3 V _{CC}	V
V _{IL2}	Input Low Voltage	$1.8 \text{ V} \le \text{V}_{CC} < 2.5 \text{ V}$		-0.5	0.25 V _{CC}	V
V _{IH1}	Input High Voltage	2.5 V ≤ V _{CC} ≤ 5.5 V		0.7 V _{CC}	V _{CC} + 0.5	V
V _{IH2}	Input High Voltage	1.8 V ≤ V _{CC} < 2.5 V		0.75 V _{CC}	V _{CC} + 0.5	V
V _{OL1}	Output Low Voltage	$V_{CC} \ge 2.5 \text{ V}, I_{OL} = 3.0 \text{ mA}$			0.4	V
V _{OL2}	Output Low Voltage	V_{CC} < 2.5 V, I_{OL} = 1.0 mA			0.2	V

Table 4. PIN IMPEDANCE CHARACTERISTICS

 $V_{CC} = 1.8 \text{ V to } 5.5 \text{ V}, T_A = -40 ^{\circ}\text{C to } +85 ^{\circ}\text{C and } V_{CC} = 2.5 \text{ V to } 5.5 \text{ V}, T_A = -40 ^{\circ}\text{C to } +125 ^{\circ}\text{C}, unless otherwise specified.}$

Symbol	Parameter	Conditions	Max	Units
C _{IN} (Note 5)	SDA I/O Pin Capacitance	V _{IN} = 0 V	8	pF
C _{IN} (Note 5)	Input Capacitance (other pins)	V _{IN} = 0 V	6	pF
I _{WP} , I _A (Note 6)	WP Input Current, Address Input Current (A ₁ , A ₂)	$V_{IN} < V_{IH}, V_{CC} = 5.5 \text{ V}$	75	μΑ
		V _{IN} < V _{IH} , V _{CC} = 3.3 V	50]
		V _{IN} < V _{IH} , V _{CC} = 1.8 V	25]
		$V_{IN} > V_{IH}$	2	

^{5.} These parameters are tested initially and after a design or process change that affects the parameter according to appropriate AEC-Q100 and JEDEC test methods.

Table 5. A.C. CHARACTERISTICS (Note 7)

 $V_{CC} = 1.8 \text{ V to } 5.5 \text{ V}, T_A = -40 ^{\circ}\text{C} \text{ to } +85 ^{\circ}\text{C} \text{ and } V_{CC} = 2.5 \text{ V to } 5.5 \text{ V}, T_A = -40 ^{\circ}\text{C to } +125 ^{\circ}\text{C}, \text{ unless otherwise specified.}$

		Standard V _{CC} = 1.8 V - 5.5 V		1	ast 3 V - 5.5 V	V _{CC} = 2.5	-Plus V - 5.5 V C to +85°C	
Symbol	Parameter	Min	Max	Min	Max	Min	Max	Units
F _{SCL}	Clock Frequency		100		400		1,000	kHz
t _{HD:STA}	START Condition Hold Time	4		0.6		0.25		μs
t _{LOW}	Low Period of SCL Clock	4.7		1.3		0.45		μs
t _{HIGH}	High Period of SCL Clock	4		0.6		0.40		μs
t _{SU:STA}	START Condition Setup Time	4.7		0.6		0.25		μs
t _{HD:DAT}	Data In Hold Time	0		0		0		μs
tsu:dat	Data In Setup Time	250		100		50		ns
t _R (Note 8)	SDA and SCL Rise Time		1,000		300		100	ns
t _F (Note 8)	SDA and SCL Fall Time		300		300		100	ns
tsu:sto	STOP Condition Setup Time	4		0.6		0.25		μs
t _{BUF}	Bus Free Time Between STOP and START	4.7		1.3		0.5		μs
t _{AA}	SCL Low to Data Out Valid		3.5		0.9		0.40	μs
t _{DH}	Data Out Hold Time	50		50		50		ns
T _i (Note 8)	Noise Pulse Filtered at SCL and SDA Inputs		50		50		50	ns
t _{SU:WP}	WP Setup Time	0		0		0		μs
t _{HD:WP}	WP Hold Time	2.5		2.5		1		μs
t _{WR}	Write Cycle Time		5		5		5	ms
t _{PU} (Notes 8, 9)	Power-up to Ready Mode		0.1		0.1		0.1	ms

Test conditions according to "A.C. Test Conditions" table.

Table 6. A.C. TEST CONDITIONS

Input Levels	0.2 x V _{CC} to 0.8 x V _{CC}
Input Rise and Fall Times	≤ 50 ns
Input Reference Levels	0.3 x V _{CC} , 0.7 x V _{CC}
Output Reference Levels	0.5 x V _{CC}
Output Load	Current Source: $I_L = 3$ mA ($V_{CC} \ge 2.5$ V); $I_L = 1$ mA ($V_{CC} < 2.5$ V); $C_L = 100$ pF

^{6.} When not driven, the WP, A1, A2 pins are pulled down to GND internally. For improved noise immunity, the internal pull-down is relatively strong; therefore the external driver must be able to supply the pull-down current when attempting to drive the input HIGH. To conserve power, as the input level exceeds the trip point of the CMOS input buffer (~ 0.5 x V_{CC}), the strong pull-down reverts to a weak current source.

^{8.} Tested initially and after a design or process change that affects this parameter.
9. t_{PU} is the delay between the time V_{CC} is stable and the device is ready to accept commands.

Power-On Reset (POR)

The CAT24M01 incorporates Power–On Reset (POR) circuitry which protects the internal logic against powering up in the wrong state.

The device will power up into Standby mode after $V_{\rm CC}$ exceeds the POR trigger level and will power down into Reset mode when $V_{\rm CC}$ drops below the POR trigger level.

This bi-directional POR behavior protects the device against brown-out failure, following a temporary loss of power.

Pin Description

SCL: The Serial Clock input pin accepts the Serial Clock signal generated by the Master.

SDA: The Serial Data I/O pin receives input data and transmits data stored in EEPROM. In transmit mode, this pin is open drain. Data is acquired on the positive edge, and is delivered on the negative edge of SCL.

A₁ and A₂: The Address pins accept the device address. These pins have on-chip pull-down resistors.

WP: The Write Protect input pin inhibits all write operations, when pulled HIGH. This pin has an on-chip pull-down resistor.

Functional Description

The CAT24M01 supports the Inter-Integrated Circuit (I^2C) Bus data transmission protocol, which defines a device that sends data to the bus as a transmitter and a device receiving data as a receiver. Data flow is controlled by a Master device, which generates the serial clock and all START and STOP conditions. The CAT24M01 acts as a Slave device. Master and Slave alternate as either transmitter or receiver. Up to 4 devices may be connected to the bus as determined by the device address inputs A_1 and A_2 .

I²C Bus Protocol

The I^2C bus consists of two 'wires', SCL and SDA. The two wires are connected to the V_{CC} supply via pull-up resistors. Master and Slave devices connect to the 2-wire bus via their respective SCL and SDA pins. The transmitting device pulls down the SDA line to 'transmit' a '0' and releases it to 'transmit' a '1'.

Data transfer may be initiated only when the bus is not busy (see A.C. Characteristics).

During data transfer, the SDA line must remain stable while the SCL line is HIGH. An SDA transition while SCL is HIGH will be interpreted as a START or STOP condition (Figure 2).

START

The START condition precedes all commands. It consists of a HIGH to LOW transition on SDA while SCL is HIGH. The START acts as a 'wake-up' call to all receivers. Absent a START, a Slave will not respond to commands.

STOP

The STOP condition completes all commands. It consists of a LOW to HIGH transition on SDA while SCL is HIGH. The STOP starts the internal Write cycle (when following a Write command) or sends the Slave into standby mode (when following a Read command).

Device Addressing

The Master initiates data transfer by creating a START condition on the bus. The Master then broadcasts an 8-bit serial Slave address. The first 4 bits of the Slave address are set to 1010, for normal Read/Write operations (Figure 3). The next 2 bits, A2, A1, select one of 4 possible memory devices connected on a single I^2C bus. The A2 and A1 bits must match the state of the external address pins. The seventh bit, a16 is the most significant internal address bit. The last bit, R/\overline{W} , specifies whether a Read (1) or Write (0) operation is to be performed. To select an internal memory location (data byte) a 17-bit address word is required: a16 bit from the Slave address byte followed by two address bytes.

Acknowledge

After processing the Slave address, the Slave responds with an acknowledge (ACK) by pulling down the SDA line during the 9th clock cycle (Figure 4). The Slave will also acknowledge the byte address and every data byte presented in Write mode. In Read mode the Slave shifts out a data byte, and then releases the SDA line during the 9th clock cycle. If the Master acknowledges the data, then the Slave continues transmitting. The Master terminates the session by not acknowledging the last data byte (NoACK) and by sending a STOP to the Slave. Bus timing is illustrated in Figure 5.

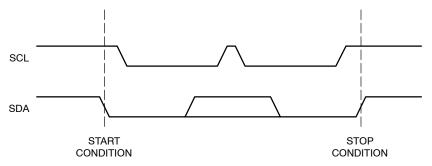


Figure 2. Start/Stop Timing

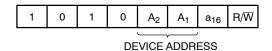


Figure 3. Slave Address Bits

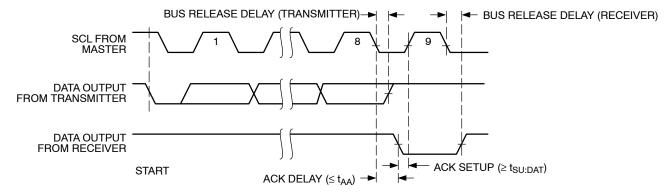


Figure 4. Acknowledge Timing

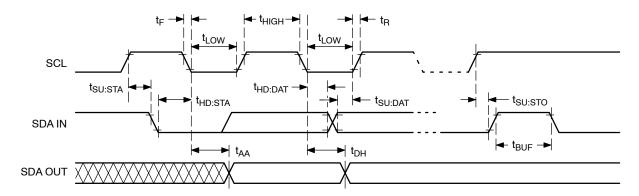


Figure 5. Bus Timing

WRITE OPERATIONS

Byte Write

In Byte Write mode the Master sends a START, followed by Slave address, two byte address and data to be written (Figure 6). The Slave acknowledges all 4 bytes, and the Master then follows up with a STOP, which in turn starts the internal Write operation (Figure 7). During internal Write, the Slave will not acknowledge any Read or Write request from the Master.

Page Write

The CAT24M01 contains 131,072 bytes of data, arranged in 512 pages of 256 bytes each. The most significant 9 bits of the address word (a16 from the Slave Address byte and most significant Address byte) identify the page and the last 8 bits identify the byte within the page. The 17-bit address word (a16 from the Slave Address byte followed by two address bytes) points to the first byte to be written. Up to 256 bytes can be written in one Write cycle (Figure 8).

The internal byte address counter is automatically incremented after each data byte is loaded. If the Master transmits more than 256 data bytes, then earlier bytes will be overwritten by later bytes in a 'wrap-around' fashion (within the selected page). The internal Write cycle starts immediately following the STOP.

Acknowledge Polling

Acknowledge polling can be used to determine if the CAT24M01 is busy writing or is ready to accept commands. Polling is implemented by interrogating the device with a 'Selective Read' command (see READ OPERATIONS).

The CAT24M01 will not acknowledge the Slave address, as long as internal Write is in progress.

Hardware Write Protection

With the WP pin held HIGH, the entire memory is protected against Write operations. If the WP pin is left floating or is grounded, it has no impact on the operation of the CAT24M01. The state of the WP pin is strobed on the last falling edge of SCL immediately preceding the first data byte (Figure 9). If the WP pin is HIGH during the strobe interval, the CAT24M01 will not acknowledge the data byte and the Write request will be rejected.

Delivery State

The CAT24M01 is shipped erased, i.e., all bytes are FFh.

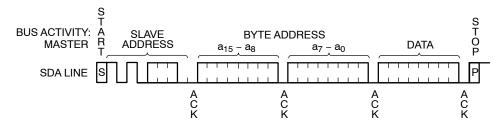


Figure 6. Byte Write Timing

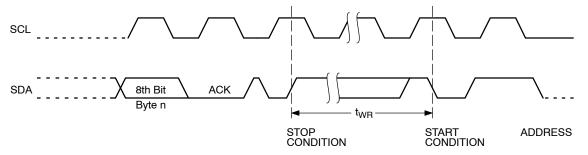


Figure 7. Write Cycle Timing

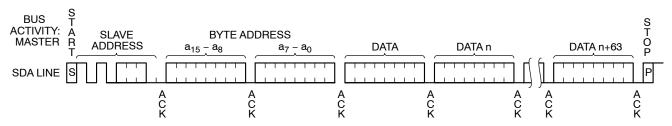


Figure 8. Page Write Timing

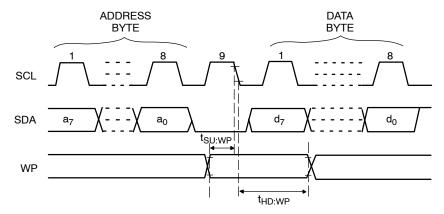


Figure 9. WP Timing

READ OPERATIONS

Immediate Address Read

In standby mode, the CAT24M01 internal address counter points to the data byte immediately following the last byte accessed by a previous operation. If that 'previous' byte was the last byte in memory, then the address counter will point to the 1st memory byte, etc.

When, following a START, the CAT24M01 is presented with a Slave address containing a '1' in the R/\overline{W} bit position (Figure 10), it will acknowledge (ACK) in the 9th clock cycle, and will then transmit data being pointed at by the internal address counter. The Master can stop further transmission by issuing a NoACK, followed by a STOP condition.

Selective Read

The Read operation can also be started at an address different from the one stored in the internal address counter. The address counter can be initialized by performing a 'dummy' Write operation (Figure 11). Here the START is followed by the Slave address (with the R/\overline{W} bit set to '0') and the desired two byte address. Instead of following up with data, the Master then issues a 2nd START, followed by the 'Immediate Address Read' sequence, as described earlier.

Sequential Read

If the Master acknowledges the 1st data byte transmitted by the CAT24M01, then the device will continue transmitting as long as each data byte is acknowledged by the Master (Figure 12). If the end of memory is reached during sequential Read, then the address counter will 'wrap–around' to the beginning of memory, etc. Sequential Read works with either 'Immediate Address Read' or 'Selective Read', the only difference being the starting byte address.

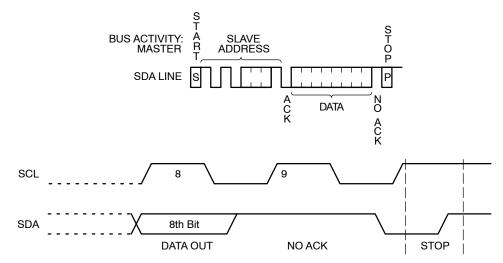
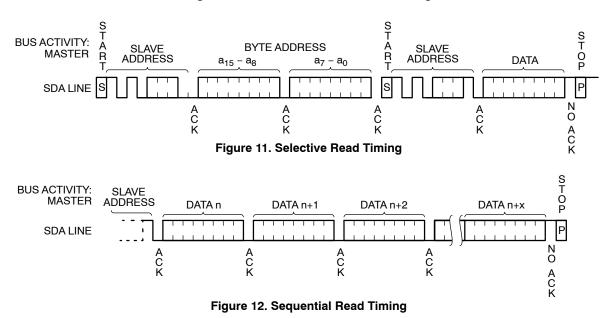
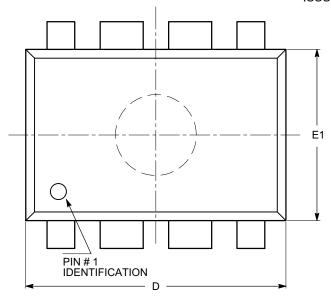


Figure 10. Immediate Address Read Timing



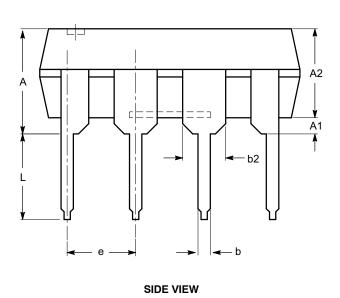
PACKAGE DIMENSIONS

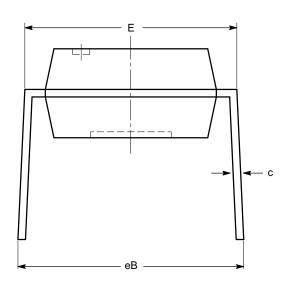
PDIP-8, 300 mils CASE 646AA-01 ISSUE A



SYMBOL	MIN	MIN NOM		
Α			5.33	
A1	0.38			
A2	2.92	3.30	4.95	
b	0.36	0.46	0.56	
b2	1.14	1.52	1.78	
С	0.20	0.25	0.36	
D	9.02	9.27	10.16	
Е	7.62	7.87	8.25	
E1	6.10	6.35	7.11	
е	2.54 BSC			
eB	7.87		10.92	
L	2.92	3.30	3.80	

TOP VIEW



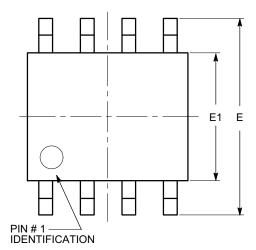


END VIEW

- (1) All dimensions are in millimeters.(2) Complies with JEDEC MS-001.

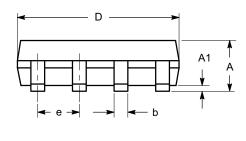
PACKAGE DIMENSIONS

SOIC 8, 150 mils CASE 751BD-01 ISSUE O

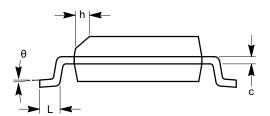


SYMBOL	MIN	NOM	MAX
Α	1.35		1.75
A1	0.10		0.25
b	0.33		0.51
С	0.19		0.25
D	4.80		5.00
E	5.80		6.20
E1	3.80		4.00
е		1.27 BSC	
h	0.25		0.50
L	0.40		1.27
θ	0°		8°

TOP VIEW



SIDE VIEW

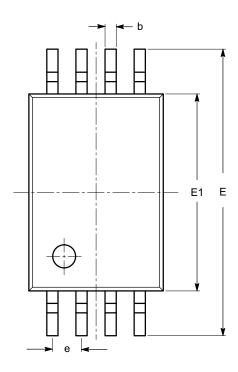


END VIEW

- (1) All dimensions are in millimeters. Angles in degrees.(2) Complies with JEDEC MS-012.

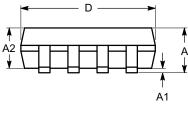
PACKAGE DIMENSIONS

TSSOP8, 4.4x3 CASE 948AL-01 ISSUE O

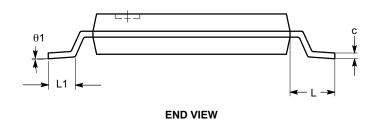


SYMBOL	MIN	NOM	MAX	
Α			1.20	
A1	0.05		0.15	
A2	0.80	0.90	1.05	
b	0.19		0.30	
С	0.09		0.20	
D	2.90	3.00	3.10	
Е	6.30	6.40	6.50	
E1	4.30	4.40	4.50	
е		0.65 BSC		
L	1.00 REF			
L1	0.50	0.60	0.75	
θ	0°		8°	

TOP VIEW



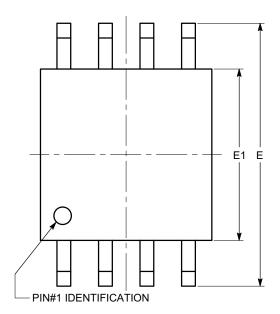
SIDE VIEW



- (1) All dimensions are in millimeters. Angles in degrees.(2) Complies with JEDEC MO-153.

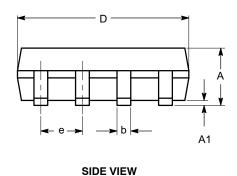
PACKAGE DIMENSIONS

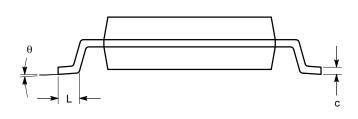
SOIC-8, 208 mils CASE 751BE-01 ISSUE O



SYMBOL	MIN	NOM	MAX
Α			2.03
A1	0.05		0.25
b	0.36		0.48
С	0.19		0.25
D	5.13		5.33
Е	7.75		8.26
E1	5.13		5.38
е		1.27 BSC	
L	0.51		0.76
θ	0°		8°

TOP VIEW





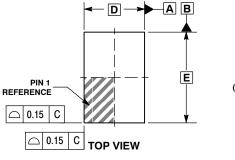
END VIEW

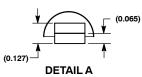
- (1) All dimensions are in millimeters. Angles in degrees.(2) Complies with EIAJ EDR-7320.

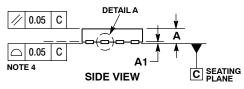
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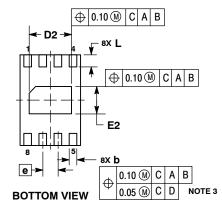
UDFN8 3.0x2.0, 0.5P

CASE 517BU-01 **ISSUE O**

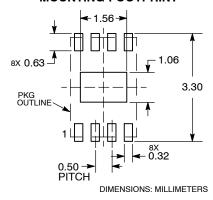








RECOMMENDED MOUNTING FOOTPRINT



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

 2. CONTROLLING DIMENSION: MILLIMETERS.

 3. DIMENSIONS 6 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25 MM FROM TERMINAL TIP.

 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS					
DIM	MIN MAX					
Α	0.45	0.55				
A1	0.00	0.05				
b	0.20	0.30				
D	2.00	BSC				
D2	1.35	1.45				
Е	3.00	BSC				
E2	0.85	0.95				
е	0.50 BSC					
L	0.35	0.45				

Example of Ordering Information (Note 10)

Device Order Number	Specific Device Marking	Package Type	Temperature Range	Lead Finish	Shipping (Note 11)
CAT24M01LE-G	24M01A	PDIP-8	-40°C to +125°C	NiPdAu	Rail
CAT24M01LI-G	24M01A	PDIP-8	–40°C to +85°C	NiPdAu	Rail
CAT24M01WE-GT3	24M01A	SOIC-8, JEDEC	-40°C to +125°C	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24M01WI-GT3	24M01A	SOIC-8, JEDEC	-40°C to +85°C	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24M01XE-T2	24M01A	SOIC-8, EIAJ	-40°C to +125°C	Matte-Tin	Tape & Reel, 2,000 Units / Reel
CAT24M01XI-T2	24M01A	SOIC-8, EIAJ	–40°C to +85°C	Matte-Tin	Tape & Reel, 2,000 Units / Reel
CAT24M01YE-GT3	M01C	TSSOP-8	-40°C to +125°C	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24M01YI-GT3	M01C	TSSOP-8	-40°C to +85°C	NiPdAu	Tape & Reel, 3,000 Units / Reel
CAT24M01HU5I-GT3	MOL	UDFN8	-40°C to +85°C	NiPdAu	Tape & Reel, 3,000 Units / Reel

^{10.} All packages are RoHS-compliant (Lead-free, Halogen-free).

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^{11.} For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.